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FX-400

Description

The FX-400 is a precision quartz-based frequency translator used to translate an input frequency such as 8 kHz, 1.544 MHz, 2.048 MHz, 19.44 MHz etc. to any specific frequency from 1.544 MHz to 1.0 GHz. The FX-400 can perform either up or down frequency conversion. The FX-400's superior jitter performance is achieved through the use of a precision VCXO or VCSO. With the use of an external multiplexer, up to 4 different input clocks can be translated to a common output frequency.

Features

- Quartz-based PLL for Ultra-Low Jitter
- Frequency Translation up to 1 GHz
- Accepts up to 4 ext.-muxed clock inputs
- LVCMS / LVDS / LVPECL Inputs compatible
- Differential LVPECL / LVDS or LVCMS Output
- Lock Detect / Loss of Signal Alarms
- Output Disable
- 20.3 x 13.7 x 5.1 mm SMT package
- RoHS/Lead Free Compliant

Applications

- Wireless Infrastructure
- 10 Gigabit FC
- 10GbE LAN / WAN
- OADM and IP Routers
- Test Equipment
- Military Communications

Block Diagram

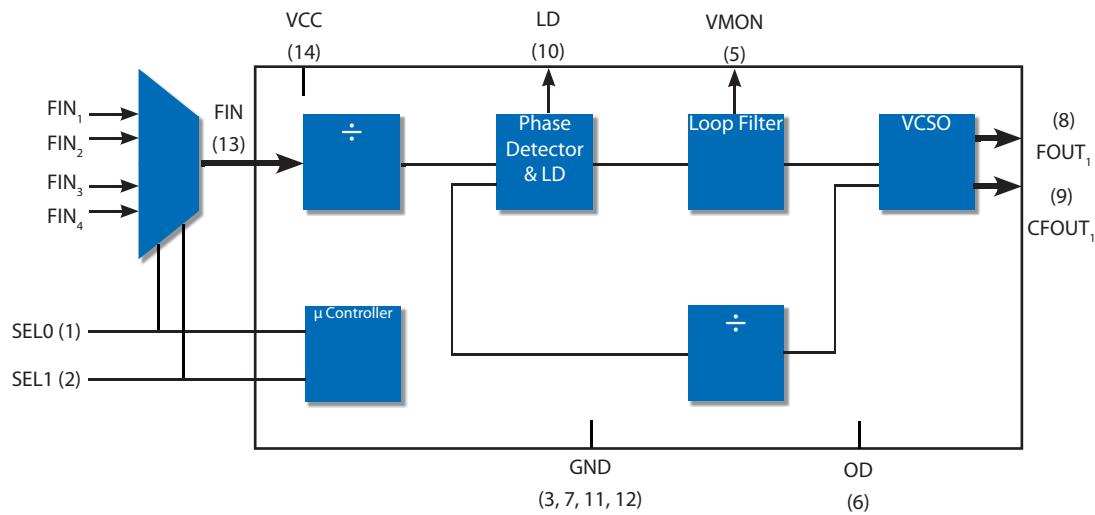


Figure 1. Functional block diagram

Absolute Maximum Ratings

Stresses in excess of the absolute maximum ratings can permanently damage the device. Functional operation is not implied at these or any other conditions in excess of conditions represented in the operational sections of this data sheet. Exposure to absolute maximum ratings for extended periods may adversely affect device reliability.

Table 2. Absolute Maximum Ratings

| Parameter | Symbol | Ratings | Unit |
|---------------------|-----------|------------|--------|
| Power Supply | V_{DD} | 6 | V |
| Storage Temperature | T_{STR} | -55 to 125 | °C |
| Soldering Temp/Tlme | T_{LS} | 260/40 | °C/sec |

Reliability

The FX-400 is capable of meeting the following qualification tests

Table 3. Environmental Compliance

| Parameter | Conditions |
|------------------------|--------------------------|
| Mechanical Shock | MIL-STD-883, Method 2002 |
| Mechanical Vibration | MIL-STD-883, Method 2007 |
| Solderability | MIL-STD-883, Method 2003 |
| Gross and Fine Leak | MIL-STD-883, Method 1014 |
| Resistance to Solvents | MIL-STD-883, Method 2016 |

Handling Precautions

Although ESD protection circuitry has been designed into the FX-400, proper precautions should be taken when handling and mounting. VI employs a human body model and a charged-device model (CDM) for ESD susceptibility testing and design protection evaluation. ESD thresholds are dependent on the circuit parameters used to define the model. Although no industry wide standard has been adopted for the CDM, a standard HBM of resistance=1.5Kohms and capacitance = 100pF is widely used and therefore can be used for comparison purposes

Table 4. Predicted ESD Ratings

| Model | Minimum | Conditions |
|----------------------|---------|--------------------------|
| Human Body Model | 500 V | MIL-STD 883, Method 3015 |
| Charged Device Model | 500 V | JEDEC, JESD22-C101 |

Reflow Profile

Table 5. Reflow Profile (IPC/JEDEC J-STD-020C)

| Parameter | Symbol | Value |
|--------------------------|-------------|-------------------------|
| PreHeat Time | t_s | 60 sec Min, 180 sec Max |
| Ramp Up | R_{UP} | 3 °C/sec Max |
| Time Above 217 °C | t_L | 60 sec Min, 150 sec Max |
| Time To Peak Temperature | t_{AMB-P} | 480 sec Max |
| Time At 260 °C | t_p | 20 sec Min, 40 sec Max |
| Ramp Down | R_{DN} | 6 °C/sec Max |

The FX-400 is qualified to meet the JEDEC standard for Pb-Free assembly. The temperatures and time intervals listed are based on the Pb-Free small body requirements. The temperatures refer to the topside of the package, measured on the package body surface. The FX-400 should not be subjected to a wash process that will immerse it in solvents. NO CLEAN is the recommended procedure. The FX-400 has been designed for pick and place reflow soldering. The FX-400 may be reflowed once and should not be reflowed in the inverted position.

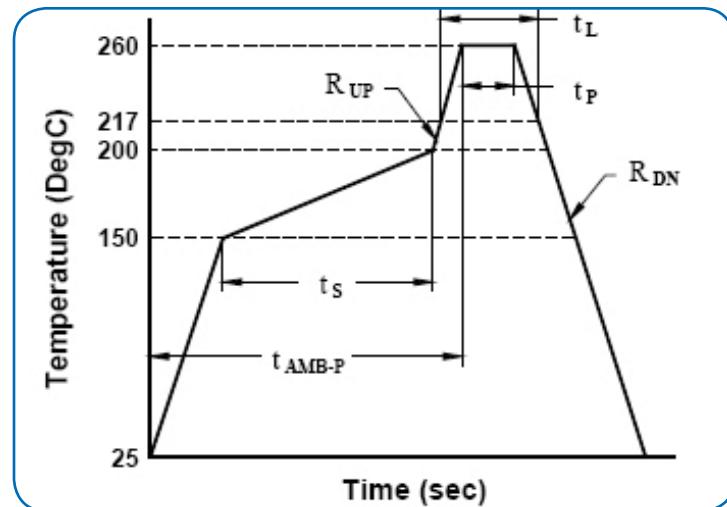


Figure 4. Suggested IR Profile

Tape and Reel

Table 6. Tape and Reel Information

| Tape Dimensions (mm) | | | | | | Reel Dimensions (mm) | | | | | | |
|----------------------|------|-----|----|----|-----|----------------------|----|------|-----|------|------|--------|
| W | F | Do | Po | P1 | A | B | C | D | N | W1 | W2 | #/Reel |
| 44 | 20.2 | 1.5 | 4 | 20 | 330 | 1.5 | 13 | 20.2 | 100 | 44.4 | 50.4 | 200 |

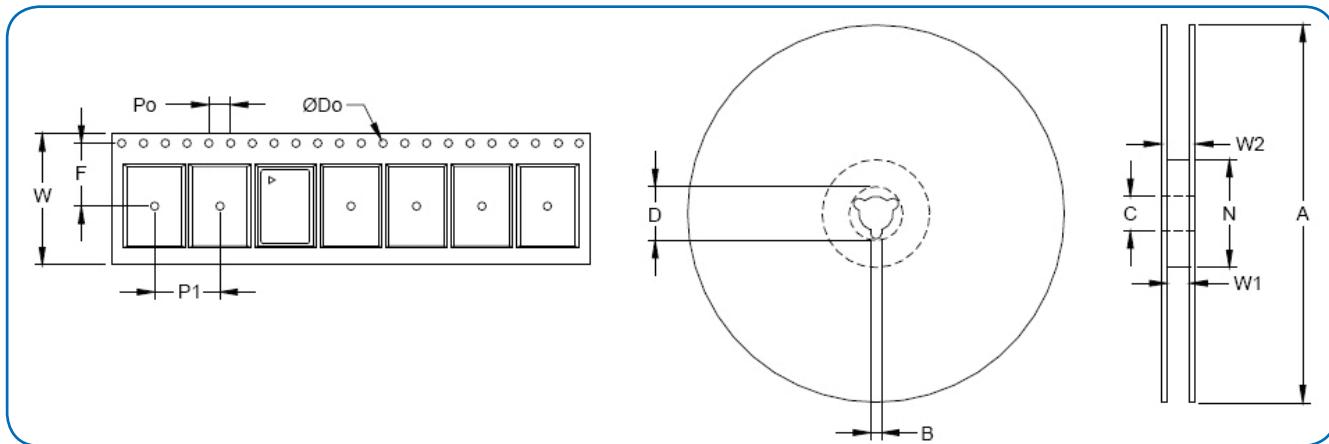


Figure 5. Tape and Reel

Pin Configuration

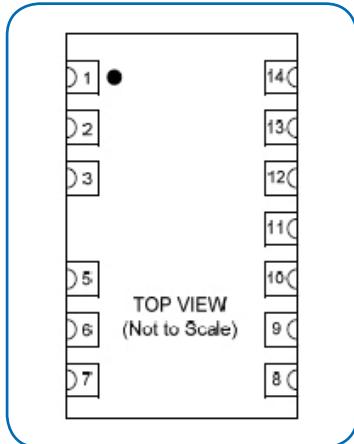


Figure 6. Pin Configuration

Table 7. Pin Functions

| Pin # | Symbol | I/O | Level | Function |
|-------|--------|-----|------------------------|--|
| 1 | SEL0 | I | LVCMOS | Frequency Select * (See Table 8) |
| 2 | SEL1 | I | LVCMOS | Frequency Select* (See Table 8) |
| 3 | GND | GND | Supply | Case and Electrical Ground |
| 4 | | | | Not present |
| 5 | VMON | O | | VCXO Control Voltage Monitor Under locked conditions VMON should be > 0.3V and <3.0V. The input frequency may be out of range if the voltage exceeds these levels |
| 6 | OD | I | LVCMOS | Output Disable Disabled = Logic "1" Enabled = Logic "0" or no connect |
| 7 | GND | GND | Supply | Case and Electrical Ground |
| 8 | FOUT | O | LCPECL, LVDS or LVCMOS | Frequency Output |
| 9 | Cfout | O | LVPECL, LVDS or LVCMOS | Complementary Frequency Output – Note for LVCMOS option this pad will be tied to GND. |
| 10 | LD | O | LVCMOS | Lock Detect Locked = Logic "1" Loss of Signal = Logic "0" |
| 11 | GND | GND | Supply | Case and Electrical Ground |
| 12 | GND | GND | Supply | Case and Electrical Ground |
| 13 | FIN | I | LVCMOS or LVPECL | Input Frequency – AC Coupled |
| 14 | VCC | VCC | Supply | Power Supply Voltage (3.3 V ±5%) |

*For applications requiring two to four input frequencies, Vectron will assign a unique part number and the Input Frequency versus SEL[1:0] settings will be provided in a Specification Control Drawing. For single input configurations it is recommended that SEL0 and SEL1 are tied to ground.

Table 8. Control Logic (LVCMOS)

| SEL0 | SEL1 | Reference Clock Input |
|------|------|-----------------------|
| 0 | 0 | F_1 |
| 0 | 1 | F_2 |
| 1 | 0 | F_3 |
| 1 | 1 | F_4 |

FX-400 Outline Diagram and Pad Layout

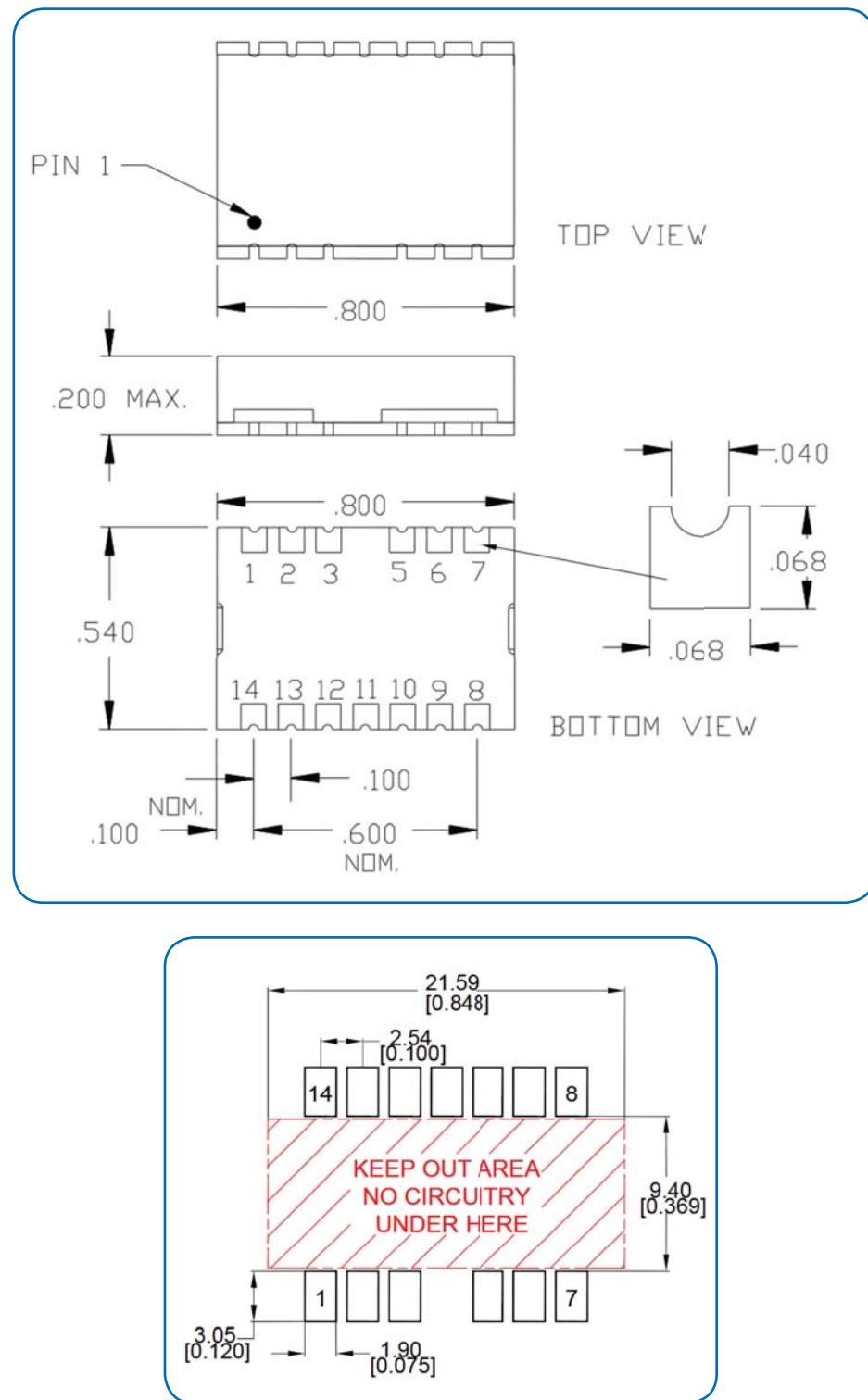


Figure 7. Outline and Pad Layout

Suggested Output Load Configurations

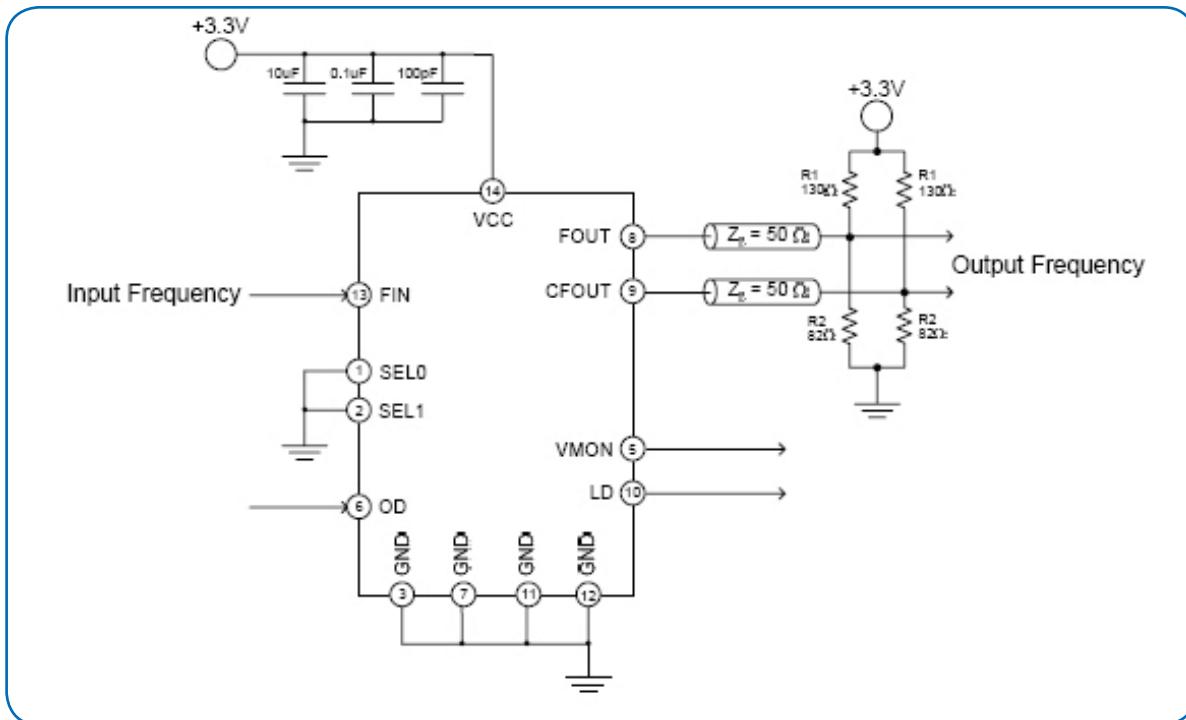


Figure 8. Single Input Frequency Translation - LVPECL Termination

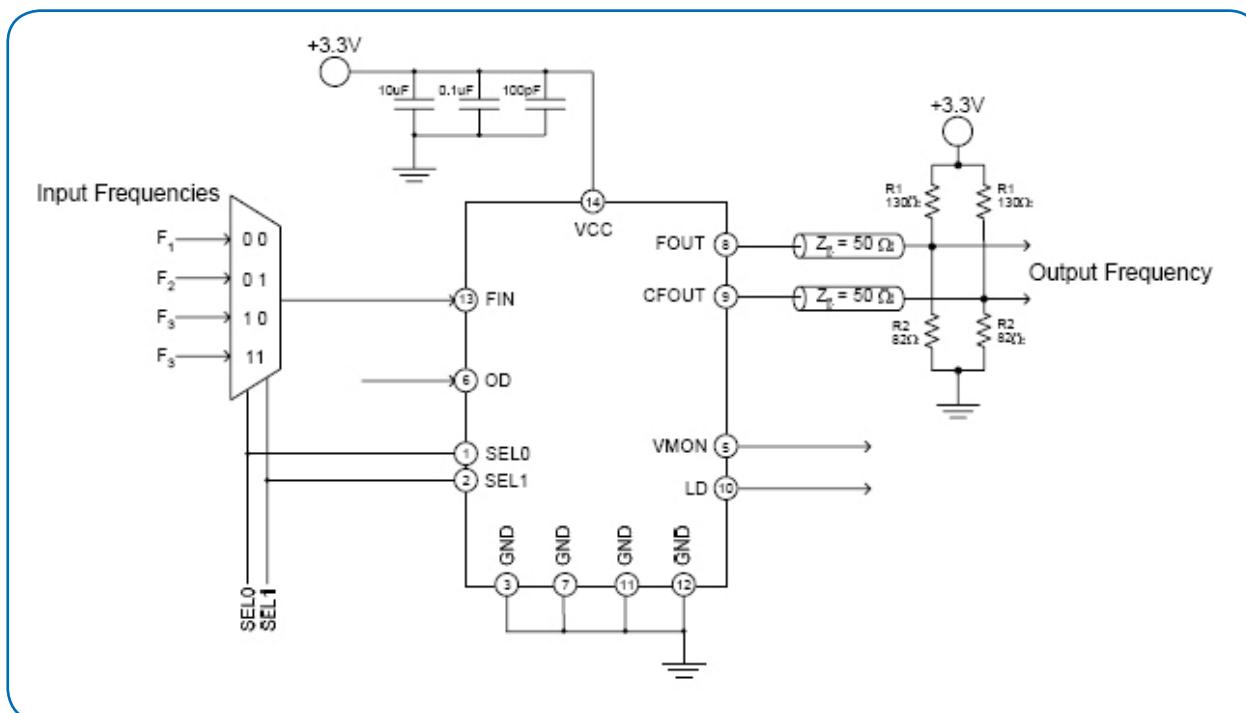


Figure 9. Four Input Frequencies Translated to Common Output Frequency – LVPECL Termination

Ordering Information

FX-400-E A E-K N N N-XX-XX

Product Family

FX: Frequency Translator

Package

400: 20.3 13.0 5.1mm

Input

E: 3.3 Vdc ±10%

Output

A: LVCMOS

C: LVPECL

D: LVDS

Operating Temperature

E: -40 to 85 °C

T: 0 to 70 °C

Output Frequency
(See Above)

Input Frequency
(See Above)

Factory Use

Factory Use

Factory Use

Absolute Pull Range

K: ± 50 ppm

S: ± 100 ppm

1. For non-listed frequencies and/or multiple input frequencies a unique part number will be assigned with the following format FX-400-XXX-SNNNN. "SNNNN" is the SCD number.

For Additional Information, Please Contact

USA:

Vectron International
267 Lowell Road
Hudson, NH 03051
Tel: 1.888.328.7661
Fax: 1.888.329.8328

Europe:

Vectron International
Landstrasse, D-74924
Neckarbischofsheim, Germany
Tel: +49 (0) 3328.4784.17
Fax: +49 (0) 3328.4784.30

Asia:

Vectron International
1F-2F, No 8 Workshop, No 308 Fenju Road
WaiGaoQiao Free Trade Zone
Pudong, Shanghai, China 200131
Tel: 86.21.5048.0777
Fax: 86.21.5048.1881

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